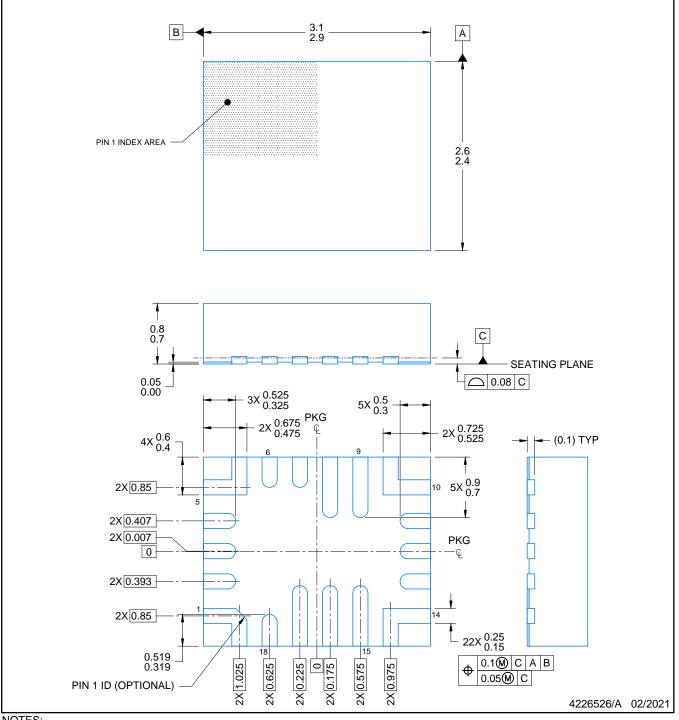
RYK0018A

PACKAGE OUTLINE

WQFN-HR - 0.8 mm max height

PLASTIC QUAD FLATPACK- NO LEAD



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing 1. per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

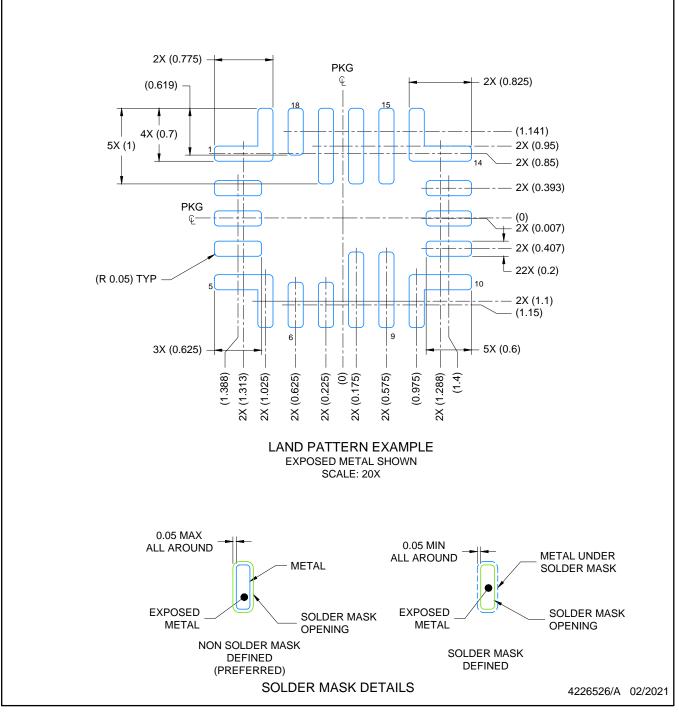


RYK0018A

EXAMPLE BOARD LAYOUT

WQFN-HR - 0.8 mm max height

PLASTIC QUAD FLATPACK- NO LEAD



NOTES: (continued)

- 3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271) .
- 4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

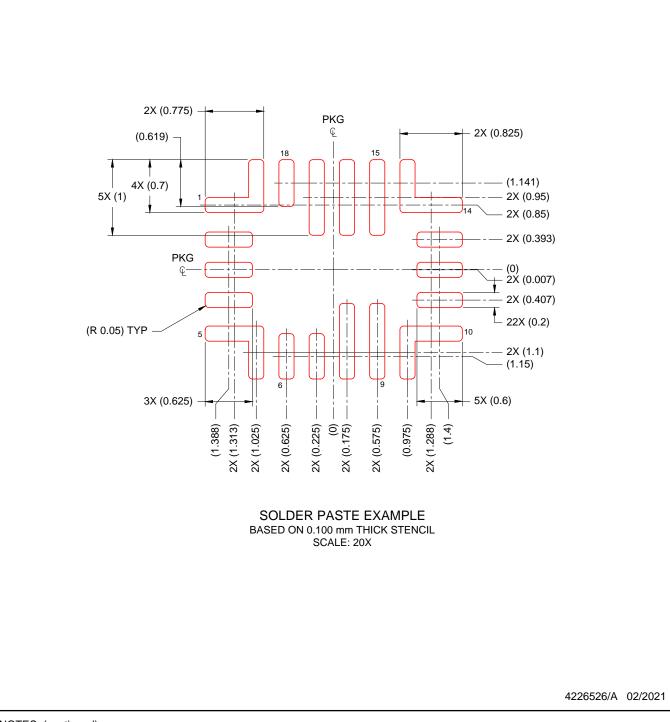


RYK0018A

EXAMPLE STENCIL DESIGN

WQFN-HR - 0.8 mm max height

PLASTIC QUAD FLATPACK- NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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